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JP 51-82400

A

AN - 1976-67628X [36]

A - [001] 012 03& 226 231 24& 250 273 331 335 351 359 360 473 546 724

CPY - ASAE

DC - A21 E14

FS - CPI

IC - C08G12/06 ; C08G14/06 ; C08G59/50 ; C08G73/02 ; C09D3/58

MC - A05-A01B A08-D01

M3 - [01] K0 H1 M311 M312 M313 M314 M315 M316 M332 M334 M322 M323 M280 M342

M340 M380 M392 M393 L420 H182 H183 M620 Q110 Q120 M510 M520 M530 M540

M782 R043 M416 M902

- [02] H4 M121 M129 M132 M135 M139 M149 M312 M313 M314 M315 M316 M332

M331 M334 M333 M321 M280 M342 M343 M344 G100 M150 M533 M532 H442 H443

H444 Q110 Q120 H402 H403 H404 H405 M510 H8 M520 M540 M782 R043 M414

M902

PA - (ASAE) ASAHI DENKA KOGYO KK

PN - JP51082400 A 19760719 DW197636 000pp

- JP57031575B B 19820706 DW198230 000pp

PR - JP19750007609 19750117

XIC - C08G-012/06 ; C08G-014/06 ; C08G-059/50 ; C08G-073/02 ; C09D-003/58

AB - J51082400 The compsn. contains (I) an epoxy resin having an av. of >1 adjacent epoxy gp. per molecule and (II) an active organic amino cpd.

obtd. by reacting a polyamine having is not <2 amino gps. having an

amt. of  $\geq 1$  active H attached to the N atom per molecule in average,

(b) thiourea or ammonium thiocyanate, (c) a phenol having  $\geq 1$  hydroxyl

gp. attached to an aromatic nucleus with  $\geq 1$  aromatic reactive

positions not being substd. with other than H and of a carbonyl cpd.

having  $\geq 1$  carbonyl gp. per molecule.

IW - QUICK HARDEN FILM FORMING EPOXY RESIN LOW HIGH TEMPERATURE

IKW - QUICK HARDEN FILM FORMING EPOXY RESIN LOW HIGH TEMPERATURE

NC - 001

OPD - 1975-01-17

ORD - 1976-07-19

PAW - (ASAE) ASAHI DENKA KOGYO KK

TI - Quick hardening film-forming epoxy resin compn - at low and high temps

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531 Rec CT/PT 25 JAN 2002

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DIALOG(R) File 351:Derwent WPI

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WPI Acc No: 1976-67628X/ 197636

Quick hardening film-forming epoxy resin compn - at low and high temps

Patent Assignee: ASAHI DENKA KOGYO KK (ASAE )

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date
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Week

JP 51082400	A	19760719			
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197636	B				
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JP 82031575	B	19820706			
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198230					
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Priority Applications (No Type Date): JP 757609 A 19750117

Abstract (Basic): JP 51082400 A

The compsn. contains (I) an epoxy resin having an av. of >1 adjacent epoxy gp. per molecule and (II) an active organic amino cpd. obtd. by reacting a polyamine having is not <2 amino gps. having an amt. of  $\geq 1$  active H attached to the N atom per molecule in average, (b) thiourea or ammonium thiocyanate, (c) a phenol having  $\geq 1$  hydroxyl gp. attached to an aromatic nucleus with  $\geq 1$  aromatic reactive positions not being substd. with other than H and of a carbonyl cpd. having  $\geq 1$  carbonyl gp. per molecule.

Derwent Class: A21; E14

International Patent Class (Additional): C08G-012/06; C08G-014/06;

C08G-059/50; C08G-073/02; C09D-003/58